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(54) EPOXY RESIN COMPOSITION

(57) Abstract:

PURPOSE: To obtain the title composition useful as a matrix resin for high- performance composite material, suitable for prepreg having excellent storage stability, comprising a tetrafunctional epoxy resin as a main component and a specific diaminodiphenylsulfone as a curing agent.

CONSTITUTION: Diaminodiphenylsulfone(DDS)

containing \leq 50wt.% particles having \leq 13 μ m particle diameter as a curing agent is dispersed in a granular state into a tetrafunctional epoxy resin as a main component and optionally the blend is mixed with a curing promoter such as imidazole compound, <50wt.% another epoxy resin (bisphenol A type epoxy resin), a thermoplastic resin, a filler, etc., to give the aimed composition. The amount of active hydrogen of amine of DDS blended is 0.4-1.5 equivalent based on epoxy group.

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